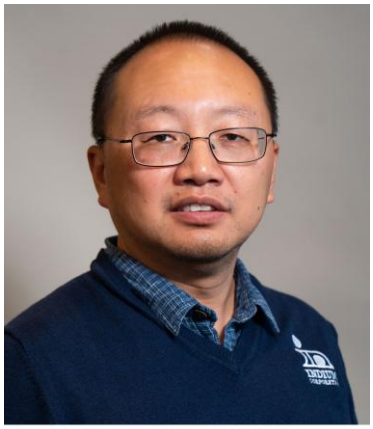
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Indium Corporation Expert to Examine TIMs Reliability for Advanced AI and HPC Applications at IEEE REPP Symposium

CLINTON, N.Y., November 10, 2026 — Indium Corporation® Research and Development Manager Jie Geng will discuss how the development of thermal interface materials (TIMs) is increasingly driven by the ability to deliver reliable thermal performance throughout a product's lifetime at the 2026 IEEE Reliability for Electronics and Photonics Packaging (REPP) Symposium, November 12-13, in Los Angeles, California.

The presentation, *The Evolution of Thermal Interface Materials: Reliability Challenges and Emerging Directions for AI and HPC Packaging*, explores TIMs technologies, from polymer-based greases and phase-change materials to metallic, carbon-based, and hybrid solutions. It examines reliability challenges, including pump-out, dry-out, creep, oxidation, interfacial degradation, thermomechanical fatigue, and long-term changes in thermal resistance. Geng will also discuss the relationship between material properties, package architecture, manufacturing constraints, and failure mechanisms from a physics-of-failure perspective. The discussion also addresses reliability qualification strategies and testing methodologies needed to evaluate next-generation TIMs under increasingly demanding AI and HPC operating conditions.



Jie Geng

Jie Geng is the R&D Manager of Thermal Interface Materials at Indium Corporation, leading the development of advanced TIM technologies and innovative thermal testing methodologies for

high-performance electronics. Since joining the company in 2016, he has played a key role in advancing commercially successful products, including Indalloy®276, Indalloy®292, and Durafuse® HR. With more than 40 peer-reviewed publications, he brings extensive expertise in materials innovation, processing, and characterization. Geng holds a Ph.D. from the University of Surrey and is a Certified SMT Process Engineer. He serves on the IEEE EPS Materials & Processes and Thermal Mechanical Technical Committees.

IEEE REPP Symposium attendees can attend Geng's presentation on November 13, 11:30 a.m. PST. To learn more about Indium Corporation's TIMs solutions, visit indium.com.

About Indium Corporation
Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Mexico, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit www.indium.com or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.linkedin.com/company/indium-corporation/.

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